SMALL FORMAT CLEANER

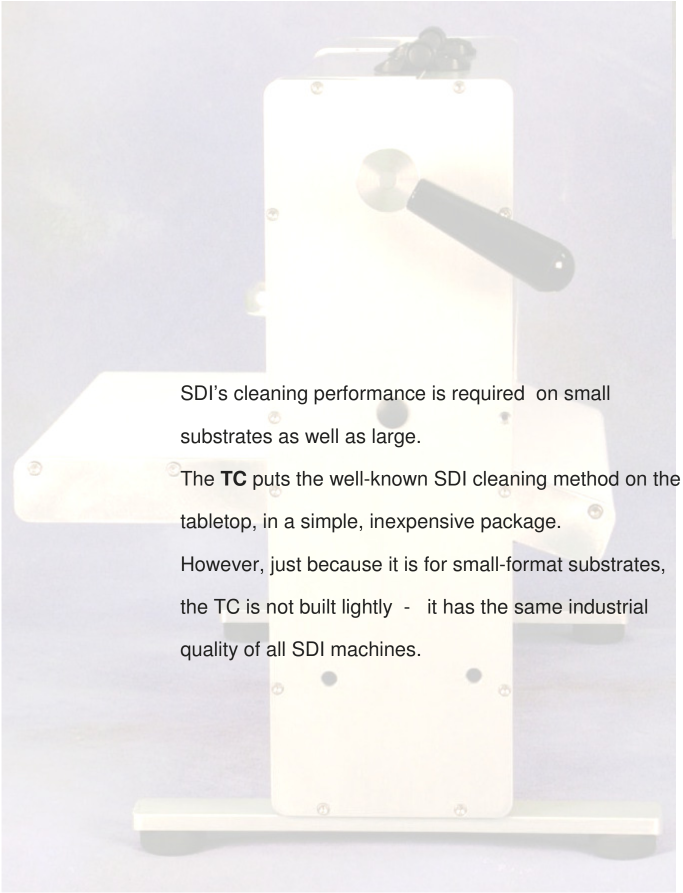
TC Range

Features

- Cleans loose dry particles from flat substrates.
- No scratching or abrasion
- ***Safestart*** puts all machine controls in one simple lever action
- Very small footprint
- Industrial quality build
- Optional anti-static at exit prevents re-attraction of airborne particles

Applications

- Small PCBs
- Ceramic wafers
- Membrane switches
- Glass / LCD production



SDI's cleaning performance is required on small substrates as well as large.

The **TC** puts the well-known SDI cleaning method on the tabletop, in a simple, inexpensive package.

However, just because it is for small-format substrates, the TC is not built lightly - it has the same industrial quality of all SDI machines.

ABOUT SDI

SDI is the largest independent manufacturer of contact cleaning systems in the world.

Founded in 1979, we offer highly engineered products dedicated to yield improvement in dust-critical production areas.

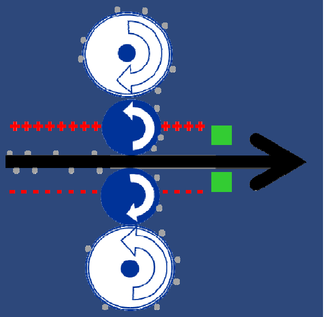
THE SDI PRINCIPLE

The SDI cleaning principle consists of three linked processes.

Specially formulated polymer rollers gently lift loose, dry contamination away from any flat surface.

The polymer rollers are in contact with an adhesive roll, onto which they transfer the lifted contamination. When saturated, the outer layer is simply peeled away.

Anti-static systems then prevent re-attraction of airborne particles to the cleaned substrate.



POLYMER ROLLERS

SDI offer a range of polymer formulations to balance the best cleaning performance against the ease of processing a particular substrate.

- **Light Blue**—silicone-based polymer suitable for most applications, cleaning particles down to 1µ in size.
- **Green**—silicone-based polymer suitable for delicate substrates, cleaning particles down to 1µ in size.
- **Yellow**—silicone-free polymer suitable for most applications, cleaning particles smaller than 1µ in size.
- **Orange**—silicone-free polymer suitable for delicate substrates, cleaning particles smaller than 1µ in size.

IMPORTANT

Material thickness is only a guide to how well a substrate can be processed.

It is *rigidity* rather than thickness that determines a substrate's ability to be cleaned by our systems.

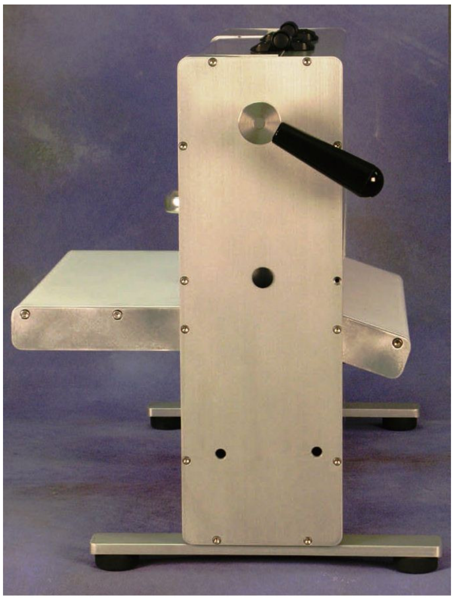
If in doubt, please send samples to our laboratory for testing at the SDI AMERICAS address.

Machine Options

- **Active Anti-Static Control**
  - The **TC** can be fitted with a 7kV corona discharge static elimination to prevent re-attraction of airborne contaminants after the cleaning process.
- **Tilt stand**
  - The Tilt Stand (pictured) allows the **TC** to operate at an angle, allowing the cleaned substrates to exit the machine using gravity.

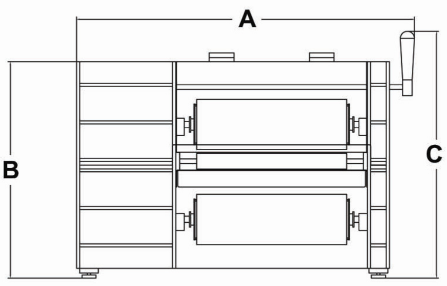
Specifications

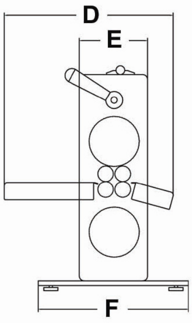
- **Substrate Dimensions**
  - Max width: 12”
  - Min length: 2.0”
  - Thickness: 0.003” - 0.200”
- **Maximum Line Speed**
  - 30fpm
- **Services Required**
  - 120V or 230V AC



Dimensions

A	29.21”
B	17.89”
C	20.33”
D	13.73”
E	5.44”
F	12.00”





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